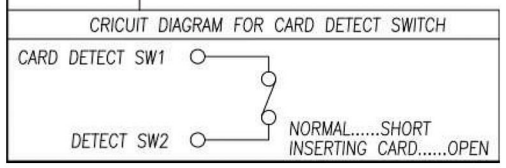


MATERIAL: Specification
 Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 SHELL: SUS

PLATING:
 Contact: Plated 50u" Ni Overall Contact Au 1U, pad Au
 Shell: Plated 50u" Ni Overall, pad 1u

Electrical:
 Current Rating : 0.5Amps.max
 Voltage Rating : 5V AC/DC
 Ambient Temperature Range : -40°C~+85°C
 Storage Temperature Range : -40°C~+85°C
 Ambient Humidity Range : 95% R.H. Max.
 Contact Resistance: 100mΩ max.
 Insulation Resistance: 1000MΩ min./500VDC
 IR Reflow Temperature: 260°C
 Mating Cycles: 3000Min Insertions

- C1:VCC
- C2:RST
- C3:CLK
- C4:RESERVED
- C5:GND
- C6:VPP
- C7:I/O
- C8:RESERVED



RoHS Compliant **HSM 玄茂科技股份有限公司**
HSUAN MAO TECHNOLOGY CO., LTD.

APPD. 核准		TOLERANCE UNLESS OTHERWISE SPECIFIED	PART NAME 品名
DWG. 製圖	Hedy	.X2±0.38 X±1"	MICRO SIM CARD CONNECTOR PUSH-PUSH TYPE
DATE 制表日	2023/10/01	.XX±0.25 X±1"	6PIN SMT TYPE H=1.42mm SELECTIVE GOLD PLATING
		.XXX±0.10 .XX±1"	BLACK COLOR REEL PACKING ROHS
		UNIT 單位	PART NO.
		M M	料號 C0664-06DASBR0R
		PAGE 張數	
		1 / 1	
		REV. 版次	
		D	

